Technical Data Sheet

Epo-Weld™ HTE-6498

incure™
ADHESIVES, EPOXIES AND COATINGS

High Temperature, Superior Strength & Chemical-Resistant Bonder

PRODUCT DESCRIPTION

Incure Epo-Weld™ 6498 (1:1) is an innovative, high performance, two-component epoxy (sealant and encapsulant) bonding material that offers effective bonding and filling properties on many substrates. Super fast-setting of pot-life of just 3 mins, bonding strength starts increasing after 15 mins and full cure within 72hrs at room temperature. Incure 6498 cures to a high gloss clear surface encapsulant with exceptional high temperature and chemical resistance. An excellent choice for use without curing equipment where speed of cure is desired. Complies to 2011/65/EU RoHS regulations.

UNCURED PROPERTIES

Chemical Type	Epoxy, 100% Solids, No Solvents			
Appearance	Two-Part Component, Clear			
Density, g/ml	1.16	Refractive Index	N.A.	@20°C
Flash Point, °C	>150	Toxicity	Very Low (Refer to MSDS)	
Viscosity, cP (rpm)	20	11,000 - 18,000	Spindle	6
Other viscosities are available upon request. If the viscosity range requested is not our standard offering, this product may be produced with a small lab fee. Email us at: support@uv-incure.com or your nearest local distributor for more information.				ASTM D2556

[1] Viscosity (cP) taken at 25°C - Call to enquiry for other viscosities.

CURED PROPERTIES

Shore Hardness, Durometer		D79 to D89	ASTM 2240
Linear Shrinkage / Expansion (-ve)		-0.05%	ASTM 570
Water Absorption at 24hrs		2.60%	[2] ISTM D2566
Tensile (PSI) * PC-PC / SS-SS / S-S / AL-AL ^ PC Substrate Failure	PC-PC / SS–SS	1,600* / 5,600*	ASTM 638
	S–S / AL–AL	9,400* / 3,600*	
Surface After Full Cure		Sleek	[2] ISTM D189
Elongation at Break		26%	ASTM 638
Thermal Range (Brittleness / Degrades) °C		-55 to 155	[2] ISTM D366
Young's Modulus of Elasticity, MPa (PSI)		1,002 (145,400)	[3] ASTM 638
Average Linear CTE, ppm/°C		218	[2] ISTM D696
Thermal Conductivity, W/mK		N.A.	[2] ISTM D696
Dielectric Constant, 100Hz		4.10	[2] ISTM D696
Volume Resistivity, ohm-cm		5.0E+15	[2] ISTM D696
Surface Resistivity, ohm		5.0E+14	[2] ISTM D696

[2] ISTM - refers to Incure Standard Test Method.
[3] ASTM 638 Young's Modulus test speed @5mm/min for rigid and semi-rigid materials, @50mm/min for non-rigid materials, unless otherwise specified.

SECONDARY HEAT CURE SCHEDULE

Continuous Oven Bake	Duration
150°C (302°F)	N.A.
125°C (257°F)	5 mins
110°C (230°F)	8 mins
100°C (212°F)	10 mins
25°C (77°F)	72 hrs

Above are recommended schedules. Request for other cure schedules may be charged at a nominal fee.

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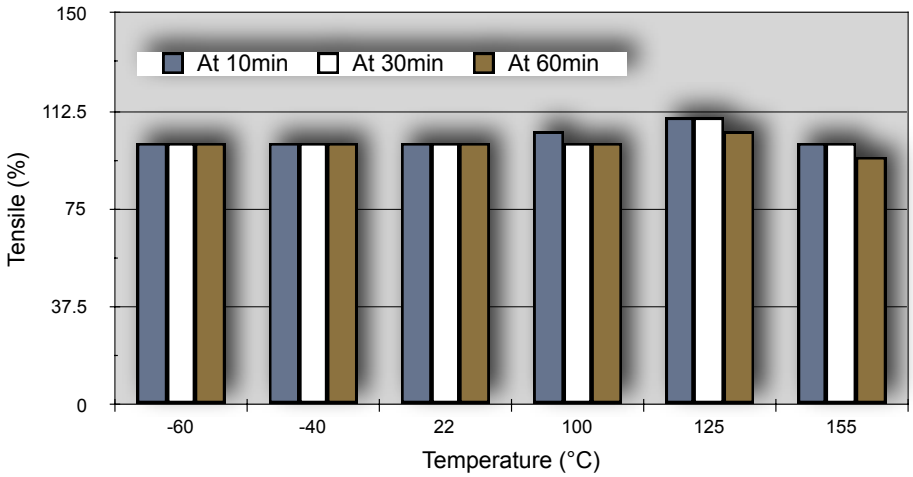
RoHS COMPLIANT | Pb LEAD FREE | HF HALOGEN FREE

TENSILE STRENGTH VS TEMPERATURE



SHELF-LIFE, STORAGE, USE AND HANDLING OF THIS PRODUCT

Shelf–Life of this unopened product is a minimum of ONE (1) year from date of manufacture. Avoid direct exposure of bottle to visible light at all times. Containers should remained covered when not in use. Product should be stored in a dark cool place of 5°C to 25°C. Transfer of product into other packages void all warranties. Users should ensure all bonding surfaces are free of grease, mold release, or any contaminants, as bonding performance will be compromised. All tests for cured bonds should be carried out at ambient temperature. For safe handling of this product, please read Material Safety Data–sheet (MSDS) prior to use. Organic solvents, such as IPA, may be used to wipe away uncured material from surfaces.

EtO and GAMMA STERILIZATION (Not Applicable for this Product)

All Incure Medical products are formulated to subject to standard sterilization methods, such as EtO and Gamma Radiation of 25 to 50 kGrays (cumulative). Enhanced moisture and thermal resistance of this product show excellent adhesion and bonding strength after one cycle of steam auto-clave test. Depending on bond design and structure of the application, users should test specific assemblies after subjecting them to the test requirements. Please consult Incure Support Team for assistance, if your devices are subjected to more than one sterilization cycles.

NOTE

The data contained in this document are furnished for information only. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein. INCURE will not be liable for any indirect, special, incidental or consequential loss or damage arising from this INCURE product, regardless of the legal theory asserted. INCURE recommends that each user adequately test its proposed use and application before repetitive use, using this data as a guide.